

Material Composition Data



Product: GSX-323

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GSX-323 - SM Crystal for Bluetooth

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Adhesive	Hydrocarbonic Solvent	Hydrocarbonic Solvent	64742-94-5	0.008	80.00
	Silicone resin	Silicon Resin	7631-86-9	0.002	20.00
BLANK	Quartz	SiO2	14808-60-7	0.109	100.00
Base	Ceramic	Al2O3	1344-28-1	5.740	68.25
	Ceramic	Au	7440-57-5	0.060	0.71
	Ceramic	CaO	1305-78-8	0.040	0.48
	Ceramic	Co	7440-48-4	0.130	1.55
	Ceramic	Cr2O3 (Non hex)	1308-38-9	0.040	0.48
	Ceramic	Cr2O3 (Non hex)	1308-38-9	0.070	0.83
	Ceramic	MgO	1309-48-4	0.040	0.48
	Ceramic	Mo	7439-98-7	0.100	1.19
	Ceramic	Ni	7440-02-0	0.500	5.95
	Ceramic	SiO2	14808-60-7	0.280	3.33
	Ceramic	W	7440-33-7	1.410	16.77
Electrode	Metal	Au	7440-57-5	0.099	99.00
	Metal	Cr	7440-47-3	0.001	1.00
Lid	Kovar	Ag	7440-22-4	0.594	13.19
	Kovar	C	7440-44-0	0.001	0.02
	Kovar	Co	7440-48-4	0.561	12.46
	Kovar	Cu	7440-50-8	0.231	5.13
	Kovar	Fe	7439-89-6	1.775	39.43
	Kovar	Mn	7439-96-5	0.012	0.27
	Kovar	Ni	7440-02-0	1.325	29.43
	Kovar	Si	7440-21-3	0.003	0.07
Total Mass:				13.131 mg	

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